Semiconductor Device Type: F3X-PDIP-18-.300in-MatteTin

Material	Substance	CAS Number	Mass of Substance in Material (mg)	Mass of Material (mg)	Percentage of Substance in Material	Percentage of Material in Product	Percentage of Substance in Product	Amount of Substance in Product (ppm)
Die				93.60	100.00%	7.50%		
	Silicon	7440-21-3	93.60		100.00%		7.50%	75000
Plating and Anode Ball				15.60	100.00%	1.25%		
	Lead	7439-92-1	0.01		0.05%		0.00%	6
	Tin	7440-31-5	15.59		99.95%		1.25%	12494
Bond Wire				2.50	100.00%	0.20%		
	Gold	7440-57-5	2.50		100.00%		0.20%	2003
Mold Compound				995.90	100.00%	79.80%		
	Phenolic Resin	Trade Secret	99.59		10.00%		7.98%	79800
	Carbon Black	1333-86-4	9.96		1.00%		0.80%	7980
	Miscellaneous	Trade Secret	39.84		4.00%		3.19%	31920
	Epoxy Resin	Trade Secret	99.59		10.00%		7.98%	79800
	Silica (Fused)	60676-86-0	746.93		75.00%		59.85%	598498
Die Attach				9.36	100.00%	0.75%		
	Silver	7440-22-4	6.69		71.50%		0.54%	5363
	Formaldehyde, Polymer with 2-(chloromethyl)oxirane and phenol	9003-36-5	1.40		15.00%		0.11%	1125
	p-tert-Butylphenyl Glycidyl Ether	3101-60-8	0.70		7.50%		0.06%	563
	Dicyandiamide	461-58-5	0.09		1.00%		0.01%	75
	Phenolic Resin	Trade Secret	0.23		2.50%		0.02%	188
	Amine	Trade Secret	0.23		2.50%		0.02%	188
Lead Frame Plating				6.55	100.00%	0.53%		
	Silver	7440-22-4	6.55		100.00%		0.53%	5250
Lead Frame				124.49	100.00%	9.98%		
	Copper	7440-50-8	121.20		97.36%		9.71%	97115
	Iron	7439-89-6	3.01		2.42%		0.24%	2415
	Lead	7439-92-1	0.01		0.01%		0.00%	11
	Phosphorus	7723-14-0	0.13		0.11%		0.01%	105
	Zinc	7440-66-6	0.13		0.11%		0.01%	105
Totals			**1248.00**	**1248.00**		**100.00%**	**100.00%**	**1000000**

The information contained in this Material Content Declaration (MCD) consists of package-level information and is not part number specific. This information is considered to be sufficiently representative of all part numbers for the package type.

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